

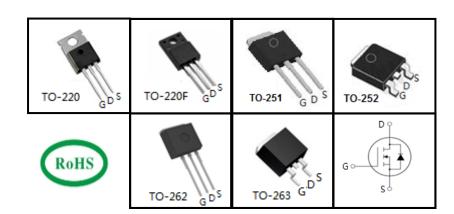
650V Super-Junction Power MOSFET

FEATURES

- Very low FOM R_{DS(on)} × Q_g
- 100% avalanche tested
- RoHS compliant

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information						
Device	TPP65R380C	TPA65R380C	TPU65R380C	TPD65R380C	TPC65R380C	TPB65R380C
Package	TO-220	TO-220F	TO-251	TO-252	TO-262	TO-263
Marking	65R380C	65R380C	65R380C	65R380C	65R380C	65R380C

Absolute Maximum Ratings T _C = 25°C, unless otherwise noted					
Parameter			Value		
		Symbol	TO-220,TO-251,TO-252 TO-262,TO-263		Unit
Drain-Source Voltage (V _{GS} = 0V)		$V_{\rm DSS}$	650		V
Continuous Drain Current		I _D	11		А
Pulsed Drain Current	(note1)	I _{DM}	33		А
Gate-Source Voltage		V_{GSS}	±30		V
Single Pulse Avalanche Energy	(note2)	E _{AS}	211		mJ
Avalanche Current	(note1)	I _{AR}	1.6		А
Repetitive Avalanche Energy	(note1)	E _{AR}	0.32		mJ
Power Dissipation (T _C = 25°C)		P _D	78	31.3	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55~+150		°C

Thermal Resistance						
		Value				
Parameter	Symbol	TO-220,TO-251,TO-252 TO-262,TO-263	TO-220F	Unit		
Thermal Resistance, Junction-to-Case	R _{thJC}	1.6	4	°C/W		
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62	80	°C/VV		



TPP65R380C, TPA65R380C, TPU65R380C, TPD65R380C, TPC65R380C, TPB65R380C

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Specifications T _J = 25°C, ur	11622 01116	Twise floted					
Parameter	Symbol	Test Conditions	Value			Unit	
			Min.	Тур.	Max.		
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	650			V	
Zero Gate Voltage Drain Current		$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	^	
Zero Gate Voltage Drain Guirent	I _{DSS}	$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	μA	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	$V_{\rm GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4	V	
Drain-Source On-Resistance (Note3)	R _{DS(on)}	$V_{GS} = 10V, I_D = 5.5A$		0.34	0.38	Ω	
Forward Transconductance (Note3)	g _{fs}	$V_{DS} = 10V, I_{D} = 5.5A$		7.8		S	
Dynamic				•			
Input Capacitance	C _{iss}	$V_{GS} = 0V$,		901		pF	
Output Capacitance	C _{oss}	$V_{DS} = 50V$,		50			
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		5.5			
Total Gate Charge	Q_g			21		nC	
Gate-Source Charge	Q_{gs}	$V_{DD} = 520V, I_{D} = 11A,$ $V_{GS} = 10V$		4.5			
Gate-Drain Charge	Q_{gd}	65		7			
Turn-on Delay Time	t _{d(on)}			41			
Turn-on Rise Time	t _r	$V_{DD} = 400V, I_{D} = 11A,$		20			
Turn-off Delay Time	t _{d(off)}	$R_G = 25\Omega$		123		ns	
Turn-off Fall Time	t _f			6.4			
Drain-Source Body Diode Characteris	stics			•			
Continuous Body Diode Current	I _s	T 0500			9.2	٨	
Pulsed Diode Forward Current	I _{SM}	T _C = 25°C			29	Α	
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 11A$, $V_{GS} = 0V$		0.9	1.2	V	
Reverse Recovery Time	t _{rr}			280		ns	
Reverse Recovery Charge	Q _{rr}	$V_R = 520V, I_F = I_S,$ $di_F/dt = 100A/\mu s$		2.8		μC	
Peak Reverse Recovery Current I _{rrm}		3. _F , 3.1 1007 ¢ p 0		17		Α	

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. I_{AS} = 1.6A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 1%

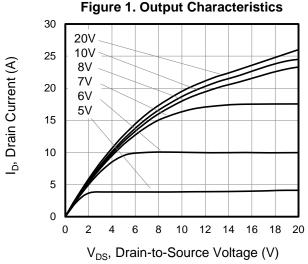
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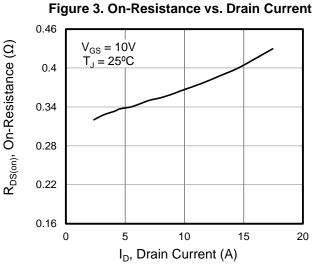
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Figure 2. Transfer Characteristics

Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted



 $V_{DS} = 10V$ $T_{\rm J} = 25^{\rm o}{\rm C}$ I_D, Drain Current (A) 16 12 $T_{J} = 150^{\circ}C$ 8 0 2 6 8 0 10 V_{GS}, Gate-to-Source Voltage (V) Figure 4. Capacitance



12

10

8

6

4

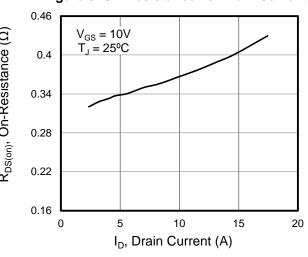
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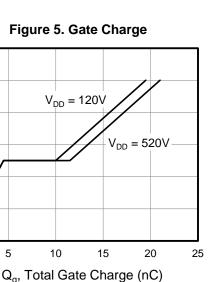
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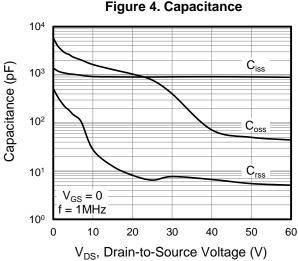
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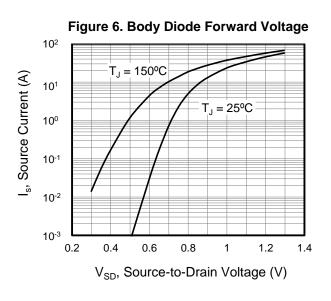
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V_{GS}, Gate-to-Source Voltage (V)







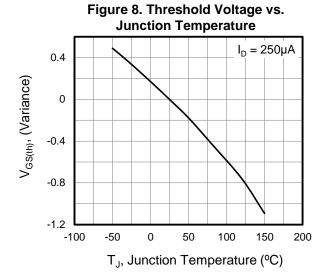




Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs. **Junction Temperature** 3 $V_{GS} = 10V$ $I_{D} = 5.5A$ 2.5 R_{DS(on)}, (Normalized) 2 1.5 1 0.5 -100 100 150 200 50 T_J, Junction Temperature (°C)

Figure 9. Transient Thermal Impedance TO-220,TO-262,TO-263,TO-251,TO-252 10¹ $\mathsf{Z}_{\mathsf{thJC}}$, Thermal Impedance (K/W) 100 10-1 D = 0.5D = 0.2D = 0.1D = 0.0510-2 D = 0.02D = 0.01Single Pulse 10-3 10-6 10⁻⁷ 10-5 10-4 10-3 10-2 10-1 T_p, Pulse Width (s)



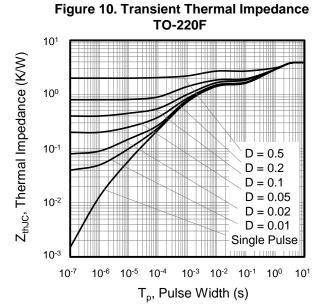




Figure A: Gate Charge Test Circuit and Waveform

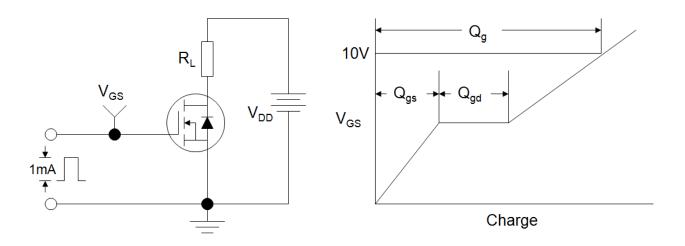


Figure B: Resistive Switching Test Circuit and Waveform

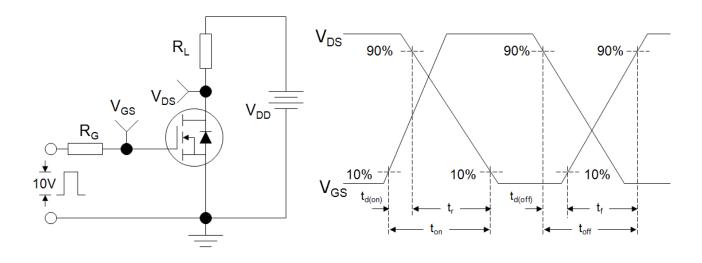
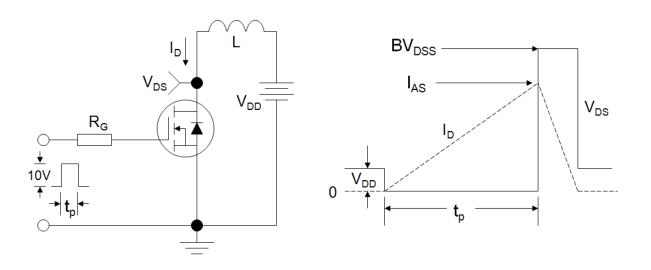
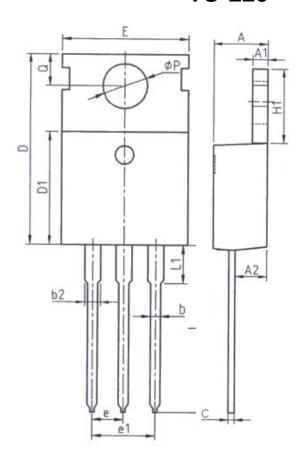
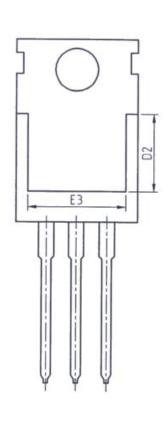


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



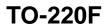
TO-220

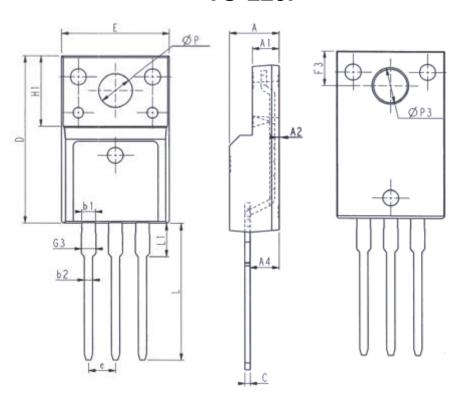




Unit: mm					
Symbol	Min.	Max.			
Α	4. 37	4. 77			
A1	1. 25	1. 45			
A2	2. 20	2. 60			
ь	0. 70	0. 95			
b2	1. 17	1. 47			
С	0. 40	0. 65			
D	15. 10	16. 10			
D1	8. 80	9. 40			
D2	5. 50	_			

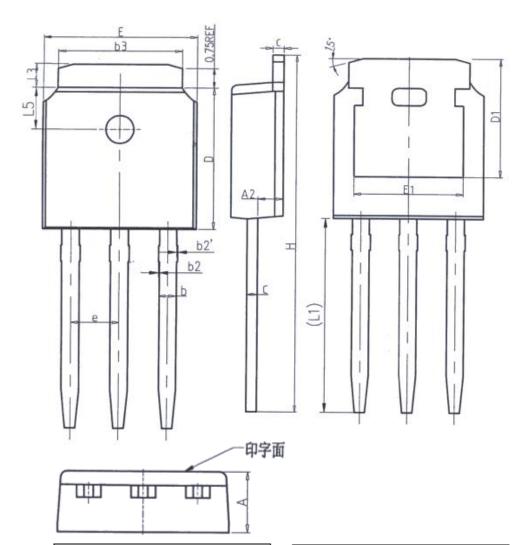
Unit: mm				
Symbol	Min.	Max.		
E	9. 70	10. 30		
E3	7. 00	ı		
е	2. 54BSC			
e1	5. 08BSC			
H1	6. 25	6. 85		
L	12. 75	13.80		
L1	-	3. 40		
P	3. 40	3. 80		
Q	2. 60	3. 00		





Unit: mm			l	Jnit: mm	n
Symbol	Min.	Max.	Symbol	Min.	Max.
E	9.96	10.36	L	12. 68	13. 28
Α	4. 50	4. 90	L1	2. 93	3. 13
A1	2. 34	2. 74	Р	3. 03	3. 38
A2	0. 30	0.60	Р3	3. 15	3. 65
A4	2. 56	2. 96	F3	3. 15	3. 45
С	0.40	0. 65	G3	1. 25	1. 55
D	15. 57	16. 17	b1	1. 18	1. 43
H1	6. 70REF		b2	0. 70	0. 95
e	2.54	1BSC			

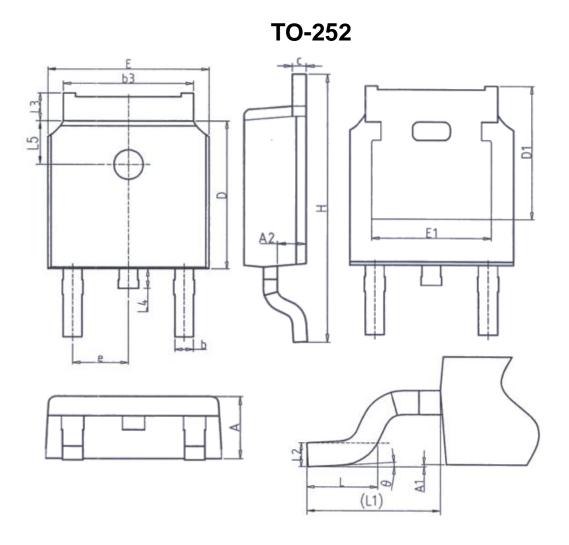
TO-251



Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A2	0. 97	1. 17		
b	0. 68	0.90		
b2	0.00	0.10		
b2′	0.00	0.10		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		

Unit: mm				
Symbol	Min.	Max.		
D1	5. 30	REF		
E	6. 40	6. 80		
E1	4. 63	-		
е	2. 286BSC			
Н	16. 22	16. 82		
L1	9. 15	9. 65		
L3	0.88	1. 28		
L5	1. 65	1. 95		

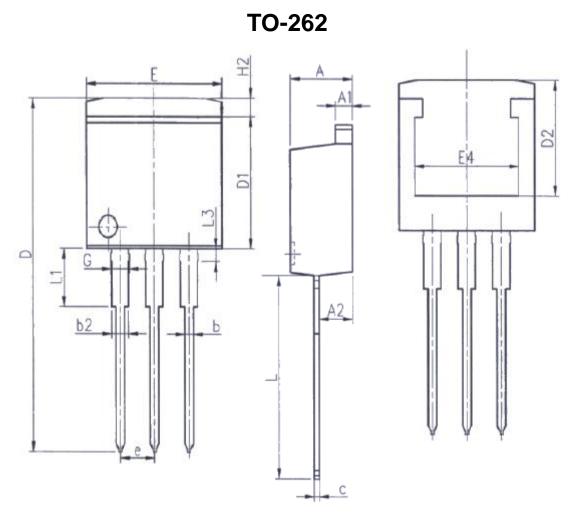




Unit: mm					
Symbol	Min.	Max.			
Α	2. 20	2. 40			
A1	0.00	0. 20			
A2	0. 97	1. 17			
b	0. 68	0.90			
b3	5. 20	5. 50			
С	0. 43	0. 63			
D	5. 98	6. 22			
D1	D1 5. 30REF				
E	6. 40	6. 80			
E1	4. 63	_			

Unit: mm					
Symbol	Min.	Max.			
е	2. 286BSC				
Н	9. 40	10.50			
L	1. 38	1. 75			
L1	2. 90REF				
L2	0. 51	IBSC			
L3	0.88	1. 28			
L4	_	1.00			
L5	1. 65	1. 95			
θ	0°	8°			

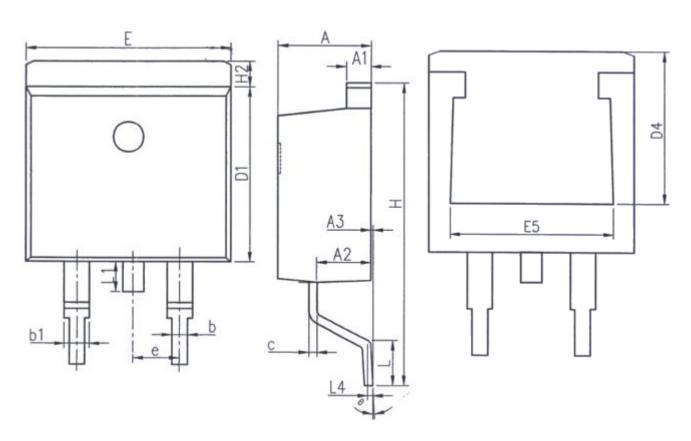




Unit: mm				
Symbol	Min.	Max.		
Α	4. 37	4. 77		
A1	1. 22	1. 42		
A2	2. 47	2. 87		
b	0. 70	0. 97		
b2	1. 17	1. 42		
С	0. 28	0.53		
D	23. 20	24. 02		
D1	8. 38	8. 90		
D2	6. 00	-		

Unit: mm			
Symbol	Min.	Max.	
E	9. 90	10. 39	
E4	7. 30	_	
е	2. 54BSC		
G	1. 25	1.50	
H2	-	1. 31	
L	13. 34	14. 10	
L1	3. 30	4. 06	
L3	0. 95	1. 15	





Unit: mm		
Symbol	Min.	Max.
Α	4. 37	4. 77
A 1	1. 22	1. 42
A2	2. 49	2. 89
A3	0.00	0. 25
b	0. 70	0. 96
b1	1. 17	1. 47
С	0. 30	0. 53
D1	8. 50	8. 90
D4	6. 60	_

Unit: mm			
Symbol	Min.	Max.	
E	9.86	10.36	
E5	7. 06	-	
е	2. 54BSC		
Н	14. 70	15. 50	
H2	1. 07	1. 47	
L	2.00	2. 60	
L1	1. 40	1. 70	
L4	0. 25BSC		
θ	0°	9°	



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